

**HEXFRED  
ULTRAFAST, SOFT RECOVERY DIODE**

$V_R = 200V$
$I_{F(AV)} = 35A$
$t_{rr} = 35ns$

**Features**

- Reduced RFI and EMI
- Reduced Snubbing
- Extensive Characterization of Recovery Parameters
- Hermetically Sealed
- Ceramic Eyelets

**Description**


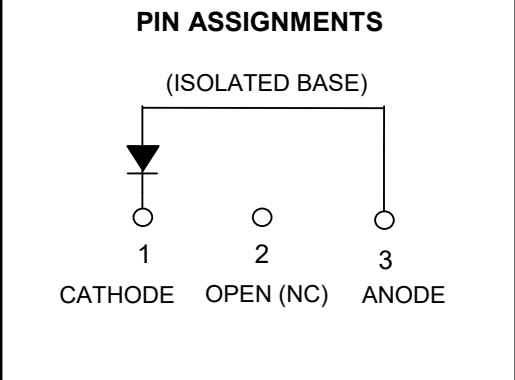
These diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and di/dt simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motors drives and other applications where switching losses are significant portion of the total losses.

**Absolute Maximum Ratings**

Characteristics	Parameter	Max.	Units
$V_R$	Cathode to Anode Voltage	200	V
$I_{F(AV)}$	Continuous Forward Current, $T_C = 80^\circ C$ ①	35	A
$I_{FSM}$	Single Pulse Forward Current, $T_C = 25^\circ C$ ②	150	A
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	125	W
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-55 to 150	$^\circ C$

**Notes:**

- ① D.C. = 50% rectangle wave
- ② 1/2 sine wave, 60Hz, Pulse Width = 8.33ms

<p><b>CASE STYLE</b></p>  <p><b>TO-254AA</b></p>	<p><b>PIN ASSIGNMENTS</b></p> <p>(ISOLATED BASE)</p>  <p>1                  2                  3 CATHODE    OPEN (NC)    ANODE</p>
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**Electrical Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)**

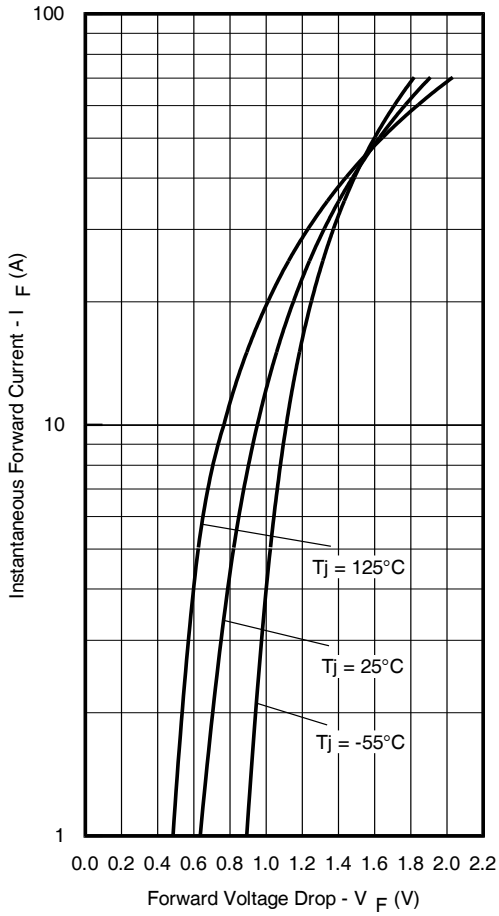
Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$V_{BR}$	Cathode Anode Breakdown Voltage	200	—	—	V	$I_R = 100\mu\text{A}$
$V_{FM}$	Max Forward Voltage See Fig. 1	—	—	1.25	V	$I_F = 20\text{A}, T_J = -55^\circ\text{C}$
		—	—	1.15		$I_F = 20\text{A}, T_J = 25^\circ\text{C}$
		—	—	1.41		$I_F = 35\text{A}, T_J = 25^\circ\text{C}$
		—	—	1.92		$I_F = 70\text{A}, T_J = 25^\circ\text{C}$
		—	—	1.01		$I_F = 20\text{A}, T_J = 125^\circ\text{C}$
$I_{RM}$	Max Reverse Leakage Current See Fig. 2	—	—	10	$\mu\text{A}$	$V_R = V_R \text{ Rated}$
		—	—	1.0	$\text{mA}$	$V_R = V_R \text{ Rated}, T_J = 125^\circ\text{C}$
$C_T$	Junction Capacitance, See Fig. 3	—	—	200	$\text{pF}$	$V_R = 200\text{V}$
$L_S$	Series Inductance	—	7.8	—	$\text{nH}$	Measured from anode lead to Cathode lead, 6mm (0.25 in) from package

**Dynamic Recovery Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)**

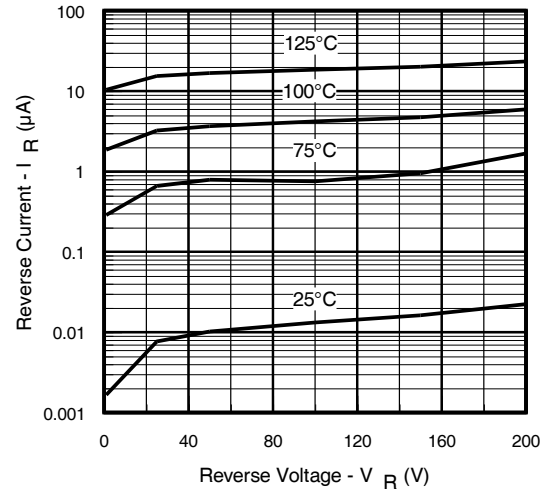
Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$t_{rr}$	Reverse Recovery Time	—	—	35	$\text{ns}$	$I_F = 1.0\text{A}, V_R = 30\text{V}, di_f/dt = 200\text{A}/\mu\text{s}$
$t_{rr1}$	Reverse Recovery Time	—	45	—	$\text{ns}$	$T_J = 25^\circ\text{C}$
$t_{rr2}$	See Fig. 5	—	68	—		$T_J = 125^\circ\text{C}$
$I_{RRM1}$	Peak Recovery Current	—	3.3	—	A	$T_J = 25^\circ\text{C}$
$I_{RRM2}$	See Fig. 6	—	7.6	—		$T_J = 125^\circ\text{C}$
$Q_{rr1}$	Reverse Recovery Charge	—	76	—	$\text{nC}$	$T_J = 25^\circ\text{C}$
$Q_{rr2}$	See Fig. 7	—	270	—		$T_J = 125^\circ\text{C}$
$di_{(rec)M}/dt1$	Peak Rate of Fall of Recovery Current	—	236	—	$\text{A}/\mu\text{s}$	$T_J = 25^\circ\text{C}$
$di_{(rec)M}/dt1$	During $t_b$ - See Fig. 8	—	1020	—		$T_J = 125^\circ\text{C}$

**Thermal - Mechanical Characteristics**

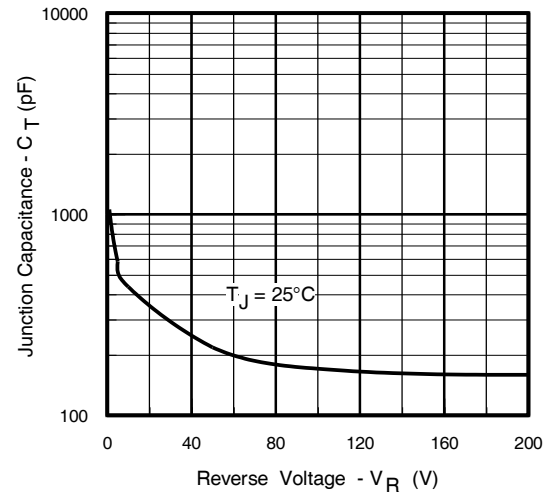
Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case, See Fig. 4	—	1.0	$^\circ\text{C}/\text{W}$
Wt	Weight	9.3	—	g



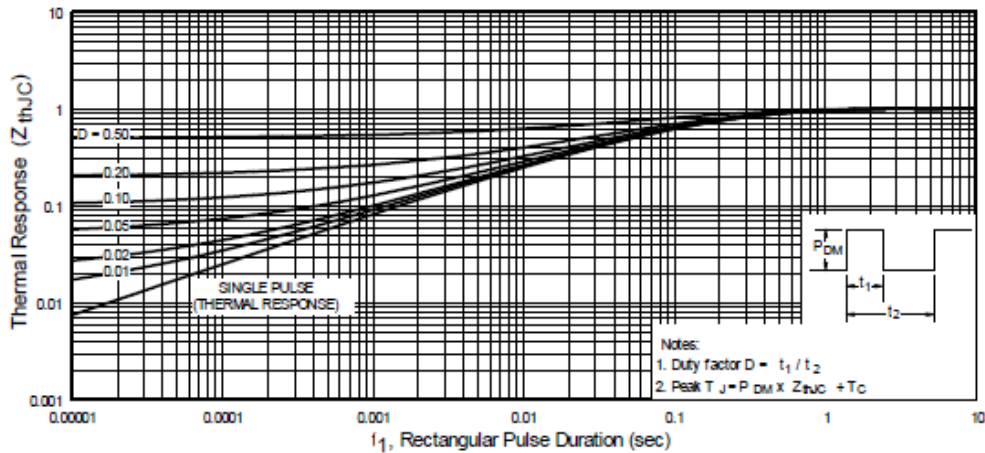
**Fig. 1** Maximum Forward Voltage Drop Vs. Instantaneous Forward Current



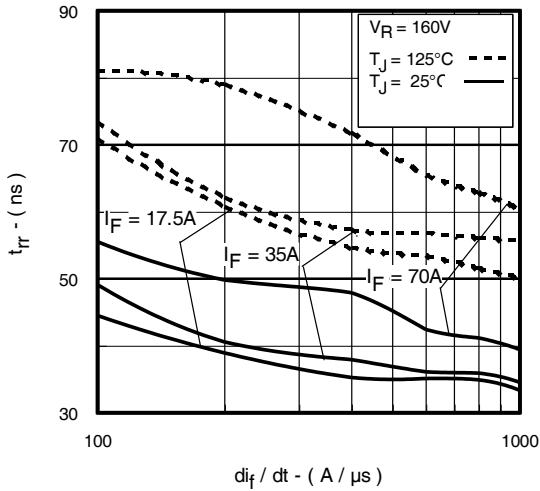
**Fig. 2** Typical Values of Reverse Current



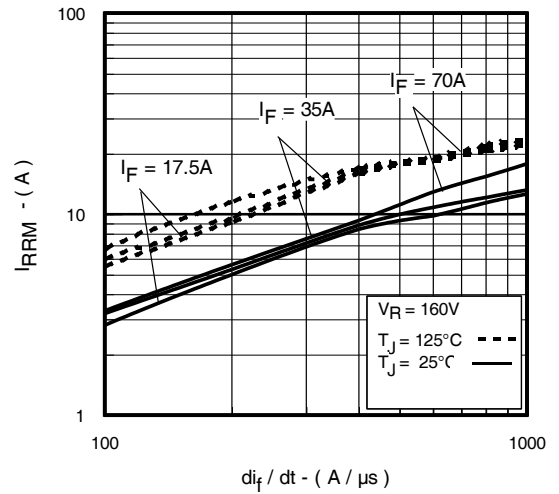
**Fig. 3** Typical Junction Capacitance Vs. Reverse Voltage



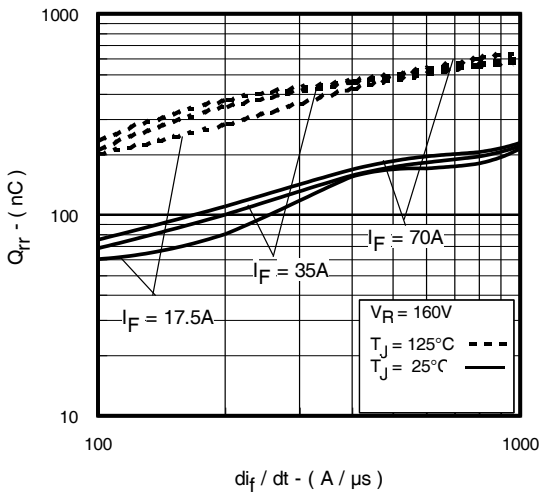
**Fig. 4** Max. Thermal Impedance  $Z_{thJC}$  Characteristics



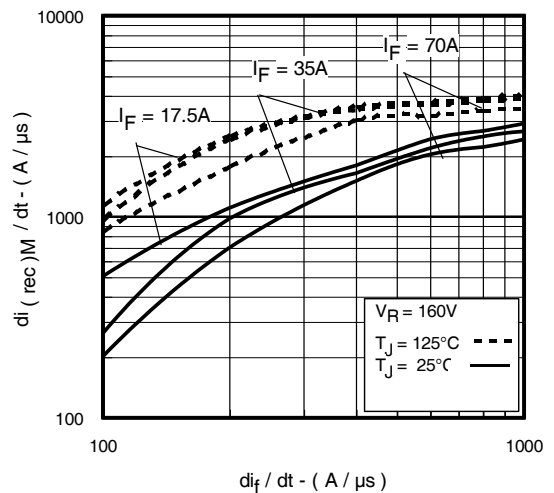
**Fig. 5** Typical Reverse Recovery Vs  $di_f/dt$



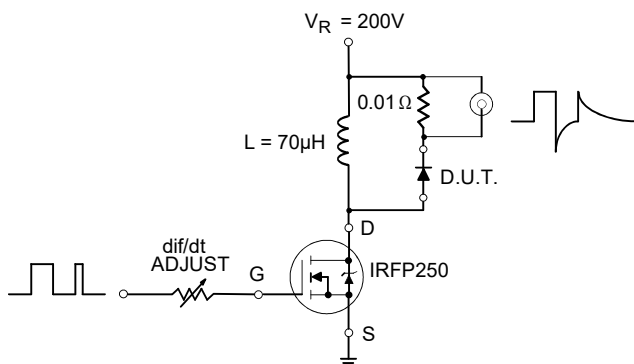
**Fig. 6** Typical Recovery Current Vs  $di_f/dt$



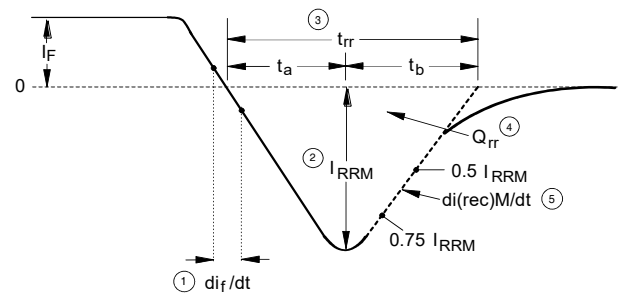
**Fig. 7** Typical Stored Charge Vs  $di_f/dt$



**Fig. 8** Typical  $di_{(rec)M}/dt$  Vs  $di_f/dt$



**Fig. 9** Typical Reverse Recovery Parameter Test Cir-



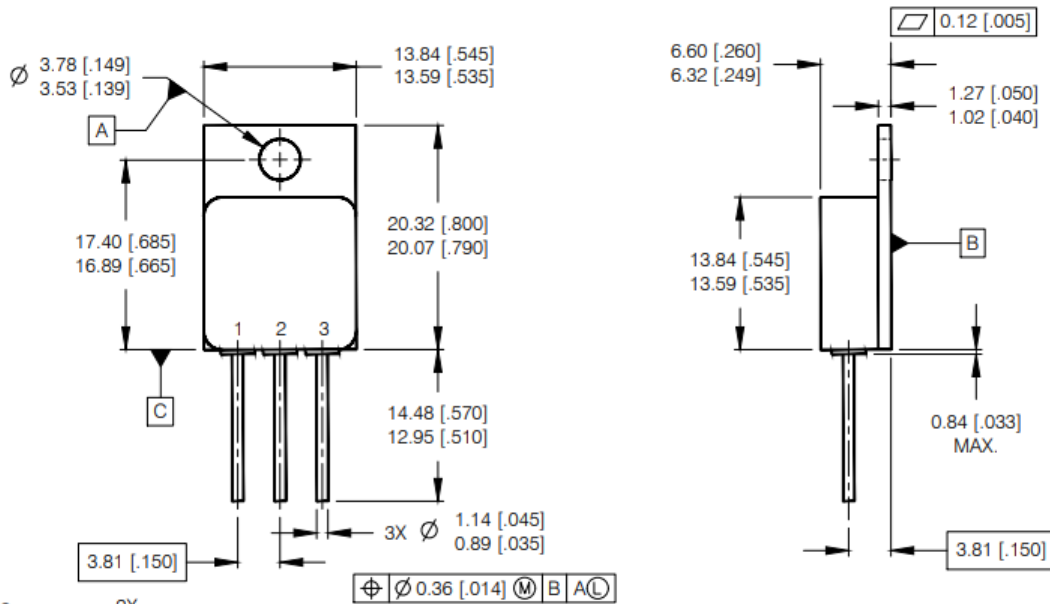
- ①  $di_f/dt$  - Rate of change of current through zero crossing.
- ②  $I_{RRM}$  - Peak reverse recovery current.
- ③  $t_{rr}$  - Reverse recovery time measured from zero crossing point of negative going  $I_F$  to point where a line passing through  $0.75I_{RRM}$  and  $0.5I_{RRM}$  extrapolated to zero current.
- ④  $Q_{rr}$  - Area under curve defined by  $t_{rr}$  and  $I_{RRM}$  -  $Q_{rr} = (t_{rr} \times I_{RRM}) / 2$
- ⑤  $di_{(rec)M}/dt$  - Peak rate of change of current during  $t_b$  position of  $t_{rr}$ .

**Fig. 10** Reverse Recovery Waveform and Definitions

Note: For the most updated package outline, please see the website: [TO-254AA](http://TO-254AA)

**Case Outline and Dimensions - Low-Ohmic TO-254AA**

REV.	DESCRIPTION	ECN	DATE
A	INITIAL RELEASE	1120_ER6904	4-3-20



- NOTES:
1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
  2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
  3. CONTROLLING DIMENSION: INCH.
  4. CONFORMS TO JEDEC OUTLINE TO-254AA.
  5. FINAL LEAD FINISH IS SOLDER ALLOY 63%Sn 37%Pb.
  6. STANDARD FINAL FINISH ON ALL TERMINALS IS SOLDER ALLOY 63%Sn 37%Pb.

**PIN ASSIGNMENTS**  
Refer to page 1.



TITLE: TO-254AA PACKAGE OUTLINE (STD & LOW OHMIC)	
DRAWING NO. D100720G-WEB	REV A

**BERYLLIA WARNING PER MIL-PRF-19500**

Package containing beryllia shall not be ground, sandblasted, machined, or have other operations performed on them which will produce beryllia or beryllium dust. Furthermore, beryllium oxide packages shall not be placed in acids that will produce fumes containing beryllium.

**IMPORTANT NOTICE**

The information given in this document shall be in no event regarded as guarantee of conditions or characteristic. The data contained herein is a characterization of the component based on internal standards and is intended to demonstrate and provide guidance for typical part performance. It will require further evaluation, qualification and analysis to determine suitability in the application environment to confirm compliance to your system requirements.

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